

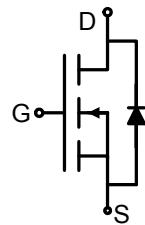
## N-Channel Enhancement Mode Power MOSFET

### Description

The SK2306 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge .This device is suitable for use as a load switch or in PWM applications.

### General Features

- $V_{DS} = 30V, I_D = 3.6A$
- $R_{DS(ON)} < 73m\Omega @ V_{GS}=4.5V$   $R_{DS(ON)} < 58m\Omega @ V_{GS}=10V$
- High power and current handing capability
- Lead free product is acquired
- Surface mount package



Schematic diagram



SOT-23 top view  
Marking and pin assignment

### Application

- Battery protection
- Load switch
- Power management

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	3.6	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	15	A
Maximum Power Dissipation	$P_D$	1.7	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	73.5	°C/W
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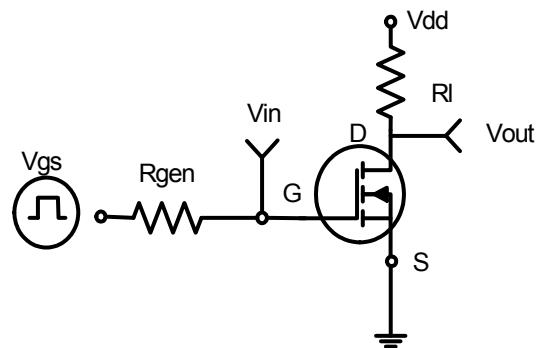
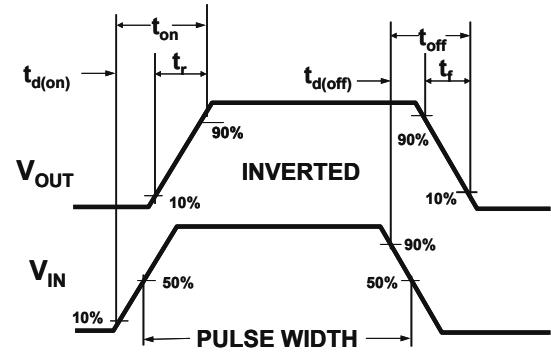
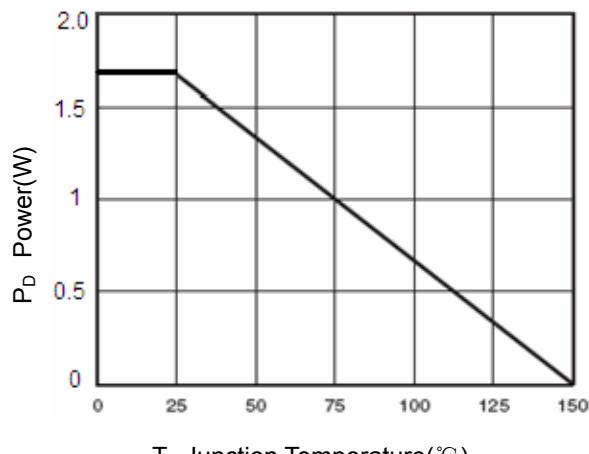
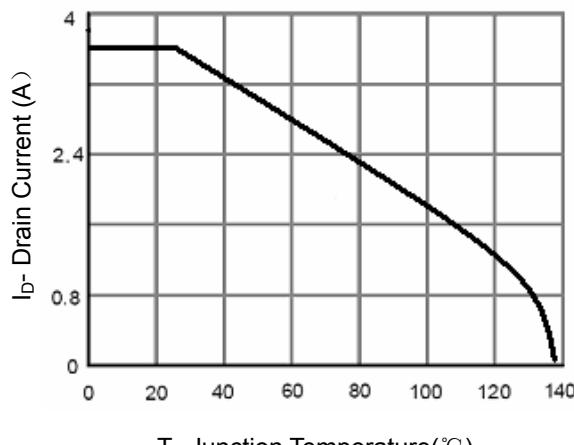
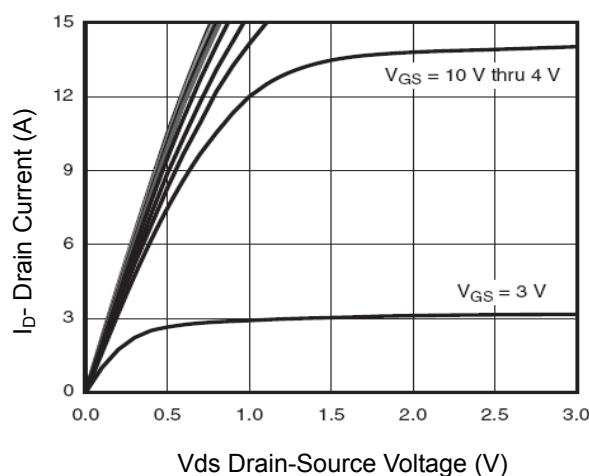
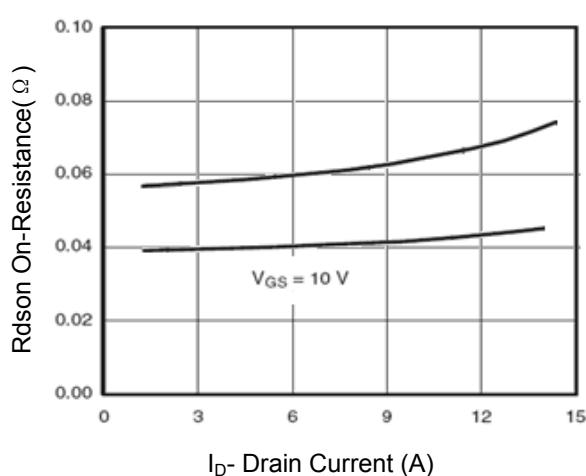
### Electrical Characteristics ( $T_A=25^\circ C$ unless otherwise noted)

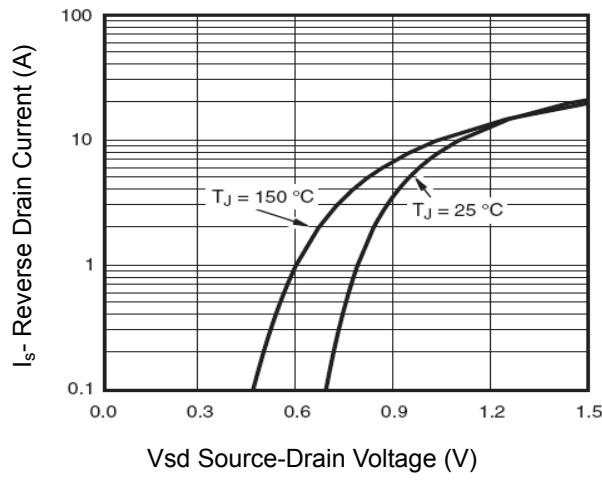
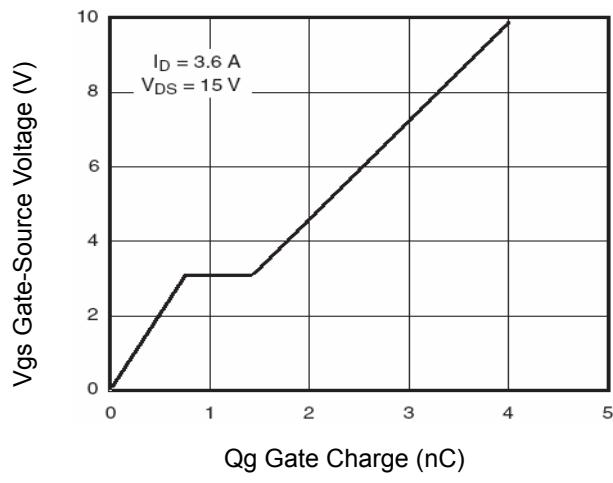
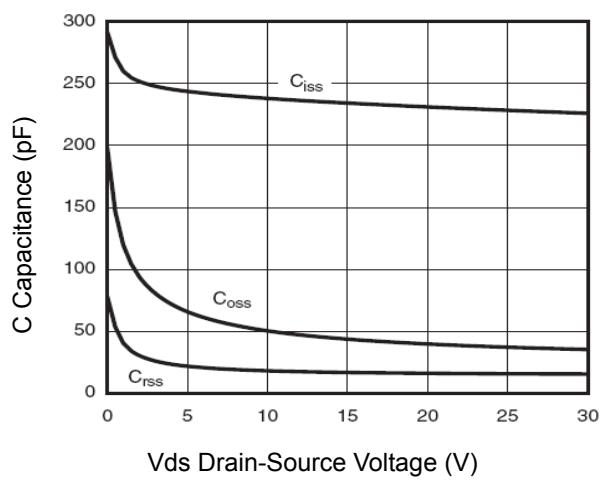
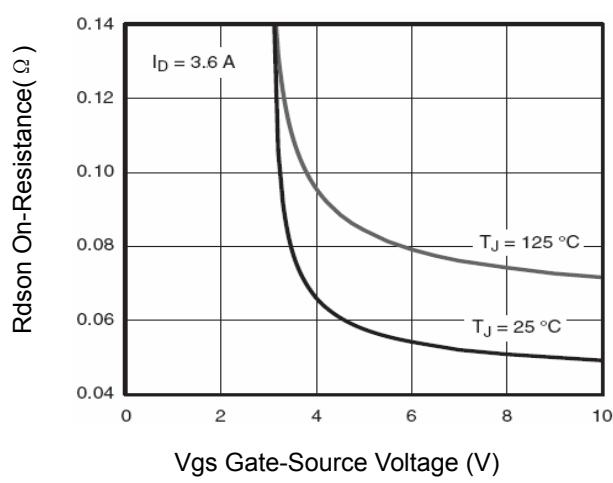
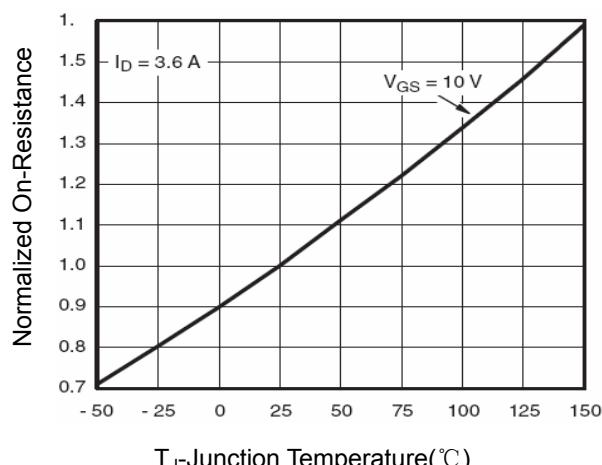
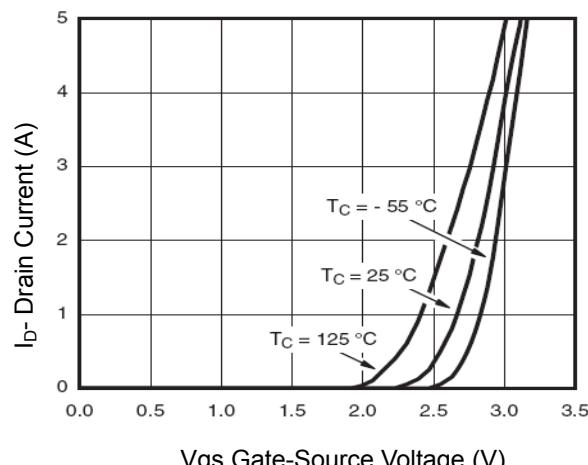
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	33	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$

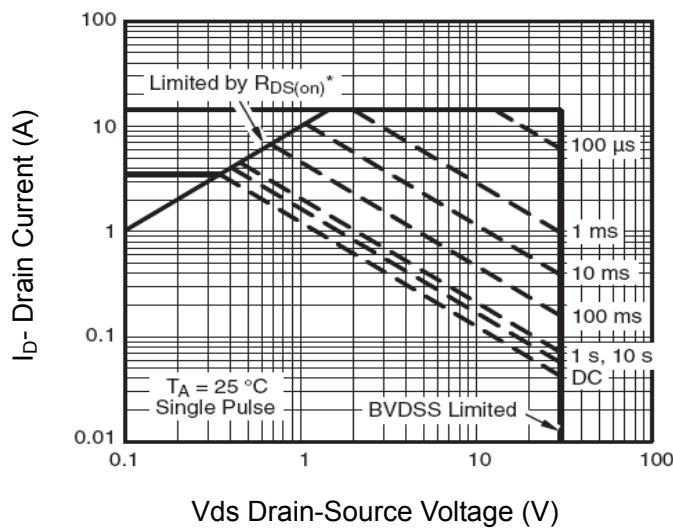
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.5	2.2	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3.1A	-	58	73	mΩ
		V <sub>GS</sub> =10V, I <sub>D</sub> =3.6A	-	40	58	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =3.6A	-	11	-	S
<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	230	-	PF
Output Capacitance	C <sub>oss</sub>		-	40	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	17	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =10V, I <sub>D</sub> =3.6A V <sub>GS</sub> =4.5V, R <sub>GEN</sub> =6Ω	-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	50	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	10	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	20	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =3.6A, V <sub>GS</sub> =10V	-	4.0	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.75	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	0.65	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =2.7A	-	0.8	1.2	V
Diode Forward Current (Note 2)	I <sub>s</sub>		-	-	1.6	A

**Notes:**

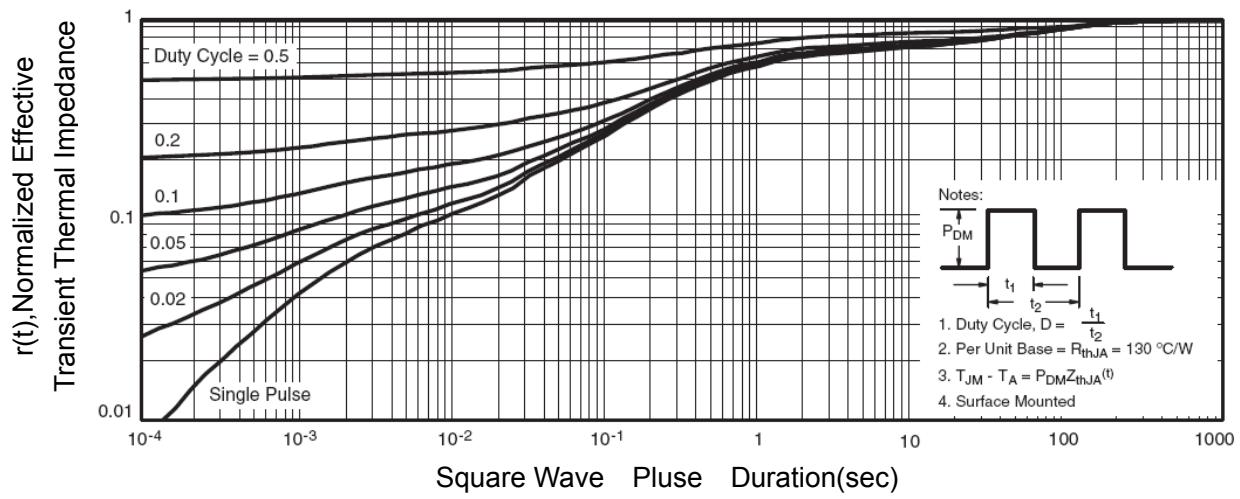
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

**Typical Electrical and Thermal Characteristics**

**Figure 1:Switching Test Circuit**

**Figure 2:Switching Waveforms**

**Figure 3 Power Dissipation**

**Figure 4 Drain Current**

**Figure 5 Output Characteristics**

**Figure 6 Drain-Source On-Resistance**





**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**